



2. (Currently Amended) The chip card of Claim 1, wherein the bonding layer protective covering layer surrounds the semiconductor chip in the second cavity from below.
3. (Original) The chip card of Claim 1, further comprising an electrically insulating or anisotropic conductive paste covering the semiconductor chip in a region of the electrical connections to the lower surface contacts of the carrier substrate, and not covering a region of the semiconductor chip which is not covered by the paste.
4. (Currently Amended) The chip card of Claim 1, wherein the bonding layer protective covering layer covers the contact-hole lines.
5. (Currently Amended) The chip card of Claim 1, further comprising recesses formed by the bonding layer protective covering layer and surrounding the contact-hole lines, wherein the bonding layer protective covering layer surrounds and seals spaces formed by the recesses.
6. (Original) The chip card of Claim 1, wherein the lower surface contact of the carrier substrate extends beyond an inner edge of a base surface of the first cavity and above the semiconductor chip within the second cavity.
7. (Original) The chip card of Claim 1, wherein the semiconductor chip is bonded to the lower surface contacts of the carrier substrate using a flip-chip method.





19. (Currently Amended) The chip card of Claim 18, wherein the ~~bonding layer~~ protective covering layer is formed from cured cyanoacrylate.
20. (Original) The chip card of Claim 12, wherein the chip card is a mobile radio card.